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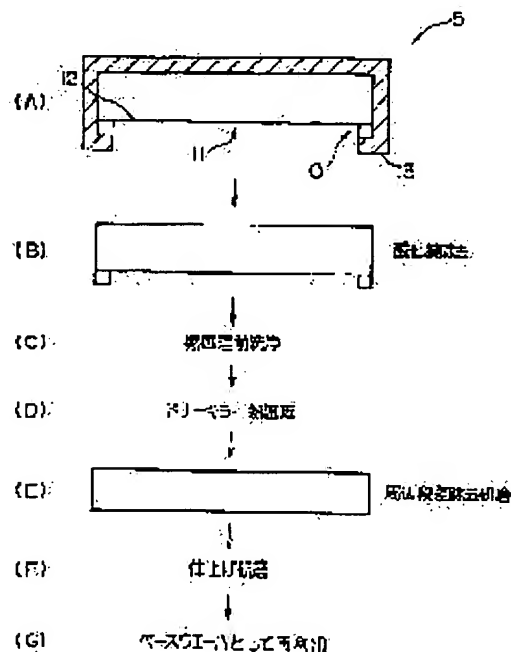
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(54) METHOD OF REUSING PEELED WAFER AND WAFER TO BE REUSED

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a method for actually reusing a peeled wafer as silicon wafer, improve the productivity of SOI wafer, and reduce its cost by performing an appropriate reprocessing to the peeled wafer which is a by-product of a hydrogen-ion peeling method.

SOLUTION: In a method of reusing a peeled wafer as a silicon wafer, by performing an reprocessing to the peeled wafer which is a by-product produced during manufacturing SOI wafers by a hydrogen-ion peeling method, as reprocessing, a surface oxide film 3 is removed (B), and a donor killer heat treatment is performed (D), next polishing is performed to remove steps on the periphery (E), and finally finish polishing is performed (F), which allows the peeled wafer to be reused.



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CLAIMS

[Claim(s)]

[Claim 1] How to reuse the exfoliation wafer characterized by performing polish which removes a surrounding level difference to an exfoliation wafer at least as said reprocessing in the approach of adding reprocessing to the exfoliation wafer by which a byproduction is carried out in case a SOI wafer is manufactured by the hydrogen ion exfoliating method, and reusing as a silicon wafer.

[Claim 2] How to reuse the exfoliation wafer according to claim 1 characterized by carrying out finishing polish as said reprocessing after the polish which removes a surrounding level difference.

[Claim 3] How to reuse the exfoliation wafer according to claim 1 or 2 characterized by removing the scaling film before the polish which removes a surrounding level difference as said reprocessing.

[Claim 4] How to reuse the exfoliation wafer of a publication in any 1 term of claim 1 characterized by performing donor killer heat treatment to an exfoliation wafer during said rework thru/or claim 3.

[Claim 5] How to reuse the exfoliation wafer characterized by reusing the exfoliation wafer reworked by any 1 term of said claim 1 thru/or claim 4 by the approach of a publication as a base wafer of a SOI wafer.

[Claim 6] How to reuse the exfoliation wafer characterized by reusing the exfoliation wafer reworked by any 1 term of said claim 1 thru/or claim 4 by the approach of a publication as a bond wafer of a SOI wafer.

[Claim 7] How to reuse the exfoliation wafer characterized by reusing the exfoliation wafer reworked by any 1 term of said claim 1 thru/or claim 4 by the approach of a publication as a silicon mirror plane wafer.

[Claim 8] The silicon wafer with which the reuse characterized by being reworked by any 1 term of said claim 1 thru/or claim 4 by the approach of a publication is presented.

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DETAILED DESCRIPTION

[Detailed Description of the Invention]

[0001]

[Field of the Invention] This invention relates to the approach of adding reprocessing to the exfoliation wafer which exfoliates after combining the wafer which carried out the ion implantation, and manufactures a SOI (silicon on insulator) wafer and by which a byproduction is carried out in the so-called hydrogen ion exfoliating method (called the smart cutting method), and reusing as a silicon wafer.

[0002]

[Description of the Prior Art] SIMOX (separation by implanted oxygen) which heat-treats at an elevated temperature and forms an oxide film after driving oxygen ion into a silicon single crystal by high concentration as a method of producing the wafer of SOI structure conventionally -- they are what is depended on law, and the technique in which the joining-together method which combines two silicon wafers which carried out mirror polishing, without using adhesives, and thin-film-izes wafer of one of the two attracts attention.

[0003] SIMOX -- since law can determine and control the thickness of the SOI layer used as a device active region by acceleration voltage at the time of oxygen ion implantation -- a thin layer -- and although there is an advantage which can obtain the high SOI layer of thickness homogeneity easily, the dependability of an embedding oxide film, the crystallinity of a SOI layer, and heat treatment at the temperature of 1300 degrees C or more are required -- etc. -- there are many problems.

[0004] On the other hand, the wafer joining-together method forms an oxide film at least in one side between two silicon mirror plane wafers of a single crystal. Join without using adhesives and association is strengthened with subsequently adding heat treatment (usually 1100 degrees C - 1200 degrees C). Since mirror polishing of the front face of a thin film is carried out and a SOI layer is formed after thin-film-izing wafer of one of the two by grinding or wet etching after that, there is an advantage that the dependability of an embedding oxide film is high and the crystallinity of a SOI layer is also good.

[0005] However, by thin-film-izing taking serious time amount upwards, since it has thin-film-ized by mechanical processing, and wafer of one of the two serves as powder etc. and it disappears, productivity will be low and will become remarkable cost quantity. And in the grinding and polish by machining, there is a fault that there is a limitation also in the thickness of the SOI layer obtained and its homogeneity. in addition, not only when the wafer joining-together method combines silicon wafers, but a silicon wafer, SiO₂ and SiC, and aluminum 2O₃ etc. -- it may couple directly with an insulating wafer and a SOI layer may be formed

[0006] The approach (the hydrogen-ion exfoliating method: technique called the smart cutting method) of exfoliating after combining the wafer which carried out the ion implantation as the manufacture approach of a SOI wafer recently, and manufacturing a SOI wafer is newly beginning to

attract attention. While this approach forms an oxide film at least in one side among two silicon wafers A hydrogen ion or rare gas ion is poured in from the top face of one silicon wafer. After making a minute air-bubbles layer (enclosure layer) form in the interior of this wafer, the field of the direction which poured in this ion is stuck with the silicon wafer of another side through an oxide film. It is the technique (refer to JP,5-211128,A) which adds the postheat treatment, exfoliates one wafer in the shape of a thin film by making a minute air-bubbles layer into a cleavage plane, adds heat treatment further, combines firmly, and is used as a SOI wafer. By this approach, a cleavage plane is a good mirror plane and the SOI wafer also with the high homogeneity of the thickness of a SOI layer is obtained comparatively easily. and not only when combining silicon wafers also in this hydrogen ion exfoliating method, but a silicon wafer -- an ion implantation -- carrying out -- this, SiO₂ and SiC, and aluminum 2O₃ etc. -- it may couple directly with an insulating wafer and a SOI layer may be formed [0007]

[Problem(s) to be Solved by the Invention] When a SOI wafer is produced by such hydrogen ion exfoliating method, the byproduction of the one exfoliation wafer of silicon will be carried out inevitably. Conventionally, since one SOI wafer was obtained from one silicon wafer on parenchyma by reusing this exfoliation wafer that carried out the byproduction in the hydrogen ion exfoliating method, it was supposed that cost can be lowered sharply.

[0008] However, the example for which a certain thing actually reused reuse of such an exfoliation wafer as a concept was unknown in what [for there to be nothing and reuse how concretely]. In investigation of this invention persons, if especially the exfoliation wafer remained as it was, it turned out that a level difference is around a wafer, the damage layer by the ion implantation exists in a front face, or surface roughness is large so that it cannot be used as a usual silicon mirror plane wafer. And when the exfoliation wafer has received heat treatment for exfoliation at least and CZ wafer is used, in the wafer, precipitation of oxygen may be started or resistivity may have separated sharply to the request value by an oxygen donor's generation.

[0009] Then, this invention was made in view of such a trouble, performs suitable reprocessing for the exfoliation wafer which carried out the byproduction in the hydrogen ion exfoliating method, offers an approach actually reusable as a silicon wafer, and actually aims at aiming at a cost cut to improvement in the productivity of a SOI wafer.

[0010]

[Means for Solving the Problem] Invention indicated to claim 1 of this invention in order to solve the above-mentioned technical problem is the approach of reusing the exfoliation wafer characterized by performing polish which removes a surrounding level difference to an exfoliation wafer at least as said reprocessing in the approach of adding reprocessing to the exfoliation wafer by which a byproduction is carried out in case a SOI wafer is manufactured by the hydrogen ion exfoliating method, and reusing as a silicon wafer.

[0011] Thus, to the exfoliation wafer which carried out the byproduction by the hydrogen ion exfoliating method, it became clear that there was a level difference on the outskirts. So, in this invention, it decided to remove by grinding a surrounding level difference as reprocessing of an exfoliation wafer. If polish removes the surrounding level difference of an exfoliation wafer, while a surrounding level difference is easily removable, removal of the damage layer of an exfoliation wafer front face and the improvement of surface roughness are also made to coincidence.

[0012] In this case, as indicated to claim 2, it is desirable as reprocessing of an exfoliation wafer to carry out finishing polish after the polish which removes a surrounding level difference. This is because the direction ground in two or more steps can make better surface roughness or display flatness of a polished surface etc. rather than finishing a polished surface only by the polish which removes a surrounding level difference, and it can consider as the reuse wafer of high quality. And since there is not necessarily no need of also performing finishing polish in one step, you may carry

out by two steps or more than it.

[0013] Moreover, as indicated to claim 3, it is desirable to remove the scaling film as reprocessing of an exfoliation wafer before the polish which removes a surrounding level difference. Thus, if the scaling film is removed before the polish which removes a surrounding level difference, it can grind to homogeneity. That is, if the oxide film has adhered to the surrounding level difference section, it will turn to a bigger level difference up, and it will become difficult to grind an oxide film to homogeneity in polish, since silicon differs from a degree of hardness.

[0014] Moreover, invention indicated to claim 4 of this invention is an approach characterized by performing donor killer heat treatment to an exfoliation wafer during rework of an exfoliation wafer. Since the oxygen donor generated in the exfoliation wafer by exfoliation heat treatment etc. by performing donor killer heat treatment is eliminable, the resistivity anomaly of an exfoliation wafer can be lost.

[0015] Invention indicated to claim 5 of this invention next, the exfoliation wafer reworked by any 1 term of said claim 1 thru/or claim 4 by the approach of a publication Are the approach of reusing as a base wafer of a SOI wafer, and invention indicated to claim 6 of this invention The exfoliation wafer reworked by any 1 term of said claim 1 thru/or claim 4 by the approach of a publication It is the approach of reusing as a bond wafer of a SOI wafer, and invention indicated to claim 7 of this invention is the approach of reusing the exfoliation wafer reworked by any 1 term of said claim 1 thru/or claim 4 by the approach of a publication as a silicon mirror plane wafer further.

[0016] Thus, since the front face is ground by homogeneity, the exfoliation wafer reworked by this invention can be used as the base wafer or bond wafer in the case of sticking two silicon wafers and producing a SOI wafer, and can be used also as a usual silicon mirror plane wafer. Since precipitation of oxygen has occurred by exfoliation heat treatment etc. in the reworked exfoliation wafer in using the exfoliation wafer by which the byproduction was especially carried out from CZ wafer as a base wafer or a usual silicon mirror plane wafer, it will become suitable in order that this may demonstrate the gettering effectiveness. Moreover, since there are no crystal defects, such as COP (Crystal Originated Particle) and an oxygen sludge, like CZ wafer in the case of the exfoliation wafer [wafer / FZ] which has the exfoliation wafer or epitaxial layer by which the byproduction was carried out, it is suitable to reuse as a bond wafer.

[0017] And invention indicated to claim 8 of this invention is a silicon wafer with which the reuse characterized by being reworked by any 1 term of said claim 1 thru/or claim 4 by the approach of a publication is presented. As mentioned above, the exfoliation wafer reworked by this invention turns into a wafer reusable as a silicon wafer. In this case, what is necessary is to thicken thickness of the exfoliating near wafer which is beforehand used in the hydrogen ion exfoliating method, and just to make it become the thickness of the wafer considered as a request in reuse after rework by polish.

[0018]

[Embodiment of the Invention] Although the gestalt of operation of this invention is explained hereafter, referring to a drawing, this invention is not limited to these. Here, drawing 1 is the flow Fig. showing an example of the production process of the SOI wafer by the approach of manufacturing a SOI wafer by the hydrogen ion exfoliating method. Moreover, drawing 2 is the process flow Fig. showing an example of the approach of reworking and reusing the exfoliation wafer of this invention.

[0019] Hereafter, this invention is explained focusing on the case where two silicon wafers are combined. First, in the hydrogen ion exfoliating method of drawing 1, at a process (a), two silicon mirror plane wafers are prepared and the bond wafer 2 used as the base wafer 1 used as the pedestal suitable for the specification of a device and a SOI layer is prepared. Next, at a process (b), one [at least] wafer of them is oxidized thermally, the bond wafer 2 is oxidized thermally here, and the oxide film 3 of about 0.1 micrometers - 2.0 micrometer thickness is formed in the front face.

[0020] Inject a hydrogen ion or rare gas ion into a front face to one side of the bond wafer 2 in which the oxide film was formed, the minute air-bubbles layer (enclosure layer) 4 parallel to a front face is made to form in it in the average penetration depth of ion at a process (c), and this impregnation temperature has desirable 25-450 degrees C. A process (d) is a process which piles up and sticks the base wafer 1 to the hydrogen ion impregnation side of the bond wafer 2 which carried out hydrogen ion impregnation through an oxide film, and wafers paste it up by contacting the front faces of two wafers under the pure ambient atmosphere of ordinary temperature, without using adhesives etc.

[0021] Next, a process (e) is an exfoliation heat treatment process divided into the exfoliation wafer 5 and the SOI wafer 6 (SOI layer 7+ pad oxide film 3+ base wafer 1) by exfoliating bordering on the enclosure layer 4, for example, if heat treatment is added at the temperature of about 500 degrees C or more under an inert gas ambient atmosphere, it will be divided into the exfoliation wafer 5 and the SOI wafer 6 by the rearrangement of a crystal, and condensation of air bubbles.

[0022] And at a process (f), in the bonding strength of the wafers stuck by the adhesion process and exfoliation heat treatment process of said process (d) and (e), since it is weak for using it at a device process as it is, as heat-of-linkage processing, hot heat treatment is performed to the SOI wafer 6, and let bond strength be sufficient thing. It is desirable to perform this heat treatment in 2 hours from 30 minutes at 1050 degrees C - 1200 degrees C for example, under an inert gas ambient atmosphere. In addition, exfoliation heat treatment of a process (e) and heat-of-linkage processing of a process (f) may be performed continuously, and exfoliation heat treatment of a process (e) and heat-of-linkage processing of a process (f) may be performed as that as which it serves to coincidence.

[0023] Next, a process (g) is a process of very little mirror polishing of the polish cost called a touch polish, and is a process which removes removal and surface roughness of the crystal defect layer which exists in the cleavage plane which is a front face of the SOI layer 7. The SOI wafer 6 of the high quality which crystal quality is high and has the high SOI layer 7 of thickness homogeneity through the above process can be manufactured (process (h)).

[0024] In such a hydrogen ion exfoliating method, the byproduction of the exfoliation wafer 5 will be carried out in the drawing 1 (e) process. Since the thickness of the SOI layer produced by the hydrogen ion exfoliating method is usually 2 microns or less in about 0.1-1.5 microns as it is thick, the exfoliation wafer 5 has sufficient thickness. Therefore, if this is reused as a silicon wafer, it will become possible to lower the manufacturing cost of a SOI wafer remarkably.

[0025] However, as the extension mimetic diagram of an exfoliation wafer was shown in drawing 2 (A), it turned out that a level difference 10 occurs in the periphery of this exfoliation wafer 5, and it becomes what cannot be used as a silicon wafer if it remains as it is. The level difference 10 of the circumference of this is generated from becoming uncombined, without combining the periphery of a bond wafer with a base wafer. Therefore, the height of this level difference becomes the thing of extent which embedded with the thickness of a SOI layer and added the thickness of an oxide film 3.

[0026] Moreover, in the stripped plane 11 of an exfoliation wafer, the damage layer 12 by hydrogen ion impregnation remained, and the surface roughness was also found by that it is bad at it compared with the usual mirror plane wafer. When local surface roughness was bad and performed etching with selectivity like alkali etching especially, it turned out that a deep pit will be formed.

[0027] Furthermore, this exfoliation wafer 5 has received exfoliation heat treatment of about 500 degrees C or more at least, and it may produce un-arranging, as an oxygen donor occurs and resistance of a wafer indicates outlying observation to be, when the wafer containing oxygen like CZ wafer is used as a bond wafer.

[0028] Then, that the above problems should be solved, this invention persons perform suitable reprocessing for the exfoliation wafer which carried out the byproduction in the hydrogen ion exfoliating method, and as a result of examining how to actually reuse as a silicon wafer, they result in

this invention. That is, first, by this invention, when manufacturing a SOI wafer by the hydrogen ion exfoliating method, polish removed the level difference of the circumference produced to the exfoliation wafer by which a byproduction is carried out.

[0029] Thus, if polish removes the surrounding level difference of an exfoliation wafer, a surrounding level difference is easily removable. For example, when the thickness of a SOI layer is 0.2 microns, a level difference can be completely removed by about 1-micron polish cost. And in case polish removes a surrounding level difference, removal of the damage layer of an exfoliation wafer front face and the improvement of surface roughness are also made to coincidence.

[0030] In this case, as reprocessing of an exfoliation wafer, it is desirable to carry out finishing polish after the polish which removes a circumference level difference. This is because the direction ground in two or more steps using abrasives with a more fine eye can make better surface roughness, display flatness, etc. of a polished surface rather than finishing a polished surface only by the polish which removes a surrounding level difference, and quality equivalent to the surface roughness of the usual silicon mirror plane wafer or display flatness can be attained. In addition, there is not necessarily no need of also performing this finishing polish in one step, and it may be performed by two steps or more than it.

[0031] Moreover, in this invention, it is desirable to remove the scaling film 3 as reprocessing of an exfoliation wafer before the polish which removes a surrounding level difference. This is because the direction which removes the scaling film 3 before the polish which removes the surrounding level difference 10 can grind to homogeneity. That is, when the oxide film 3 has adhered to the surrounding level difference section 10, a level difference will become higher and an oxide film is because silicon differs from a degree of hardness, so the inside of an exfoliation wafer side becomes is hard to be ground in homogeneity. Removal of an oxide film can perform an exfoliation wafer easily by being immersed into fluoric acid.

[0032] In this way, the damage layer by the level difference in an exfoliation wafer periphery and the hydrogen ion impregnation in a stripped plane and the surface roughness of a stripped plane can be removed, and a reuse wafer with the front face which any inferiority does not have compared with the usual mirror plane wafer can be obtained.

[0033] Moreover, when an exfoliation wafer is a CZ wafer in this invention, it is desirable to perform donor killer heat treatment during rework of an exfoliation wafer. Since an exfoliation wafer exfoliates by exfoliation heat treatment of about 500 degrees C or more, it will have received such [naturally] low-temperature heat treatment. If low-temperature heat treatment is performed to the silicon wafer which contains oxygen like CZ wafer, an oxygen donor will occur, for example, it is known well that phenomena, like the resistivity of a p-type silicon wafer becomes high unusually may arise. Therefore, also in the exfoliation wafer by which a byproduction is carried out by the hydrogen ion exfoliating method, by exfoliation heat treatment, an oxygen donor may arise and the resistivity of an exfoliation wafer may become unusual. for this reason -- for example, in case the thickness of a wafer is measured, the problem that thickness of an exfoliation wafer cannot be measured with the measuring instrument of the capacitive sensing method currently generally used arises.

[0034] Therefore, in this invention, by performing donor killer heat treatment during rework, the oxygen donor generated in the exfoliation wafer is eliminated, and the resistivity anomaly of an exfoliation wafer was lost by exfoliation heat treatment etc. What is necessary is just made to carry out heat treatment for 20 minutes as an approach which should just add heat treatment of 600 degrees C or more, and is commonly used as this donor killer heat treatment as generally carried out, for example at 650 degrees C.

[0035] And during rework of an exfoliation wafer, before that washing or etching of a wafer is performed heat-treats as mentioned above many especially, washing and etching are performed in many cases so that a wafer may not be polluted in heat treatment. In this case, since a cure, such as a

deep pit being formed and making [many] polish cost at a next polish process, is needed when etching or washing with selectivity like alkali etching is performed, since local surface roughness is bad and also has a damage layer, an exfoliation wafer like this invention is not desirable.

[0036] In this way, since it has the field condition ground by the completely same homogeneity as the usual silicon mirror plane wafer, the silicon wafer reworked by the approach of above-mentioned this invention can be used as a raw material wafer of a lamination SOI wafer, and may be used as a silicon wafer for production of the usual integrated circuit etc. Moreover, you may use as the so-called substrate of an epitaxial wafer, and especially the application of the reuse is not limited.

[0037] In this case, since precipitation of oxygen has occurred in the reworked exfoliation wafer by the thermal oxidation processing before hydrogen ion impregnation (usually 900 degrees C or more), and exfoliation heat treatment of about 500 degrees C or more in using the exfoliation wafer with which this invention was reworked as a base wafer or a usual silicon mirror plane wafer, it will become suitable in order that this may demonstrate the so-called in thorin chic gettering effectiveness (the IG effectiveness). Moreover, if an exfoliation wafer is used as the base wafer or bond wafer at the time of producing a SOI wafer, since one SOI wafer can be obtained from one silicon wafer on parenchyma, the manufacturing cost of a SOI wafer can be decreased remarkably.

[0038] In addition, although the exfoliation wafer reworked by this invention is reused as a desired silicon wafer, it thickens thickness of the bond wafer which is an exfoliating near wafer which is beforehand used in the hydrogen ion exfoliating method a little from the thickness for which it is needed with a reuse wafer, and it is made to serve as thickness of the wafer considered as a request in reuse after rework by polish.

[0039] However, as mentioned above, in order to remove the surrounding level difference of an exfoliation wafer by polish by this invention, it is based also on the thickness of a SOI layer, but even if it can remove a level difference completely by about 1 micron [at most] polish cost and performs washing accompanied by subsequent finishing polish and etching etc., a machining allowance 10 microns or less is enough on the whole. Thickening thickness of the bond wafer to be used beforehand also seems therefore, not to become a problem.

[0040]

[Example] Although the example of this invention is given and being explained concretely hereafter, this invention is not limited to these. (Example) The conductivity type manufactured the SOI wafer in p mold by the hydrogen ion exfoliating method resistivity followed the process shown in drawing 1 (a) - (h) using the silicon mirror plane wafer 20 ohm-cm and whose diameter are 150mm. The thing thick about 8 microns was used for the thickness of the bond wafer 2 by the average of the thickness of the base wafer 1. Making [in addition] thickness of a SOI layer into 0.2 microns, the main conditions, such as an ion implantation, are as follows.

1) Pad oxide-film thickness : 400nm (0.4 microns) 2 hydrogen impregnation conditions: H⁺ Ion, impregnation energy 69keV Impregnation dosage 5.5×10^{16} /cm² 3 exfoliation heat-treatment conditions: N₂ Bottom of gas ambient atmosphere, and 500 degree-Cx 30 minutes 4 heat-of-linkage processing conditions: N₂ The bottom of a gas ambient atmosphere, 1100 degree-Cx2 hour [0041] In this way, although the SOI wafer of the high quality which has a SOI layer with a thickness of 0.2 microns was producible, the byproduction of the exfoliation wafer 5 was carried out at the process (e) of drawing 1. It decided to add reprocessing according to process [of drawing 2] (A) - (G), and to reuse this exfoliation wafer as a base wafer.

[0042] First, the unsettled circumference configuration of the exfoliation wafer 5 of drawing 2 (A) was measured by scanning with a sensing-pin type granularity plan. The measurement result was shown in drawing 3 (A). In the periphery of the exfoliation wafer 5, the level difference 10 resulting from the part which became uncombined in the circumference at the time of lamination has arisen so

that clearly from this drawing. And it turns out that the height of the level difference 10 of the circumference of it becomes more than value extent that applied the thickness (0.2 microns) of a SOI layer, and the thickness (0.4 microns) of an oxide film.

[0043] Moreover, when the surface roughness of the stripped plane 11 of the unsettled exfoliation wafer 5 of drawing 2 (A) was measured on the 250-micron square with the phase shift interference method and it measured on the 1-micron square by the atomic force microscope method, they were an average of 0.43nm and 8.3nm in the RMS value (square mean square root granularity), respectively. This value is a value very worse than the surface roughness of the usual silicon wafer by which mirror polishing was carried out, and especially the value in a 1-micron angle is a value of 10 usual times or more, and understands that local ***** is large for a stripped plane.

[0044] Next, in drawing 2 (B), the surface oxide film 3 was removed by immersing an exfoliation wafer into fluoric acid. Fluoric acid was used as the HF50% water solution. And it measured by scanning again the circumference configuration of an exfoliation wafer where the oxide film was removed, with a sensing-pin type granularity plan, and the result was shown in drawing 3 R> 3 (B). It turns out that the level difference [a little] higher than the thickness (0.2 microns) of a SOI layer has arisen at the periphery of the exfoliation wafer 5 so that clearly from this drawing.

[0045] Next, in drawing 2 (C), washing before heat treatment was carried out so that an exfoliation wafer might not be polluted. This washing performed two-step washing of (the ammonia/hydrogen peroxide solution), and (a hydrochloric acid/hydrogen peroxide solution) widely known as the so-called RCA washing. At this time, it is made not to perform the so-called alkali cleaning with an etching operation of the anisotropy using caustic alkali of sodium etc. strong as mentioned above.

[0046] And if washing before heat treatment finished, after measuring the resistivity of an exfoliation wafer, donor killer heat treatment was performed to the exfoliation wafer (drawing 2 (D)). Heat treatment conditions were set as for 20 minutes at 650 degrees C. The resistivity of an exfoliation wafer was again measured after heat treatment. Consequently, it was set to 20-ohmcm that whose the rear-face resistivity of an exfoliation wafer was 400-500-ohmcm, and surface resistivity was more than 3000-ohmcm it is the resistivity of the beginning [rear face / front] after donor killer heat treatment in the measurement before heat treatment.

[0047] Next, in drawing 2 (E), polish which removes a surrounding level difference to the exfoliation wafer which donor killer heat treatment ended was performed. What is necessary is just to make polish be the same as that of the equipment and the conditions which grind the usual silicon wafer. It is 500 g/cm², putting an exfoliation wafer between vertical surface plates, and carrying out inverse rotation of the surface plate mutually by 50rpm in this invention. The stripped plane was ground supplying a polish slurry to a polished surface having applied the load.

[0048] At this time, the result of having investigated the relation between the machining allowance of polish and the height of a surrounding level difference was shown in drawing 4 . This drawing shows that a surrounding level difference is fully removable, if 1 micron is also ground as polish cost.

[0049] Moreover, it measured by scanning again the circumference configuration of the exfoliation wafer which carried out surrounding level difference removal polish of polish cost 5 Miquelon with a sensing-pin type granularity plan, and the result was shown in drawing 3 (C). It turns out that the level difference of the periphery of an exfoliation wafer is removed finely, and it has become a circumference configuration reusable enough as a silicon wafer so that clearly from this drawing.

[0050] Finally, in drawing 2 (F), finishing polish was performed and reprocessing of an exfoliation wafer was ended. The machining allowance by polish by surrounding level difference removal polish and the whole finishing polish was made to become about 8 microns at this time. And when the surface roughness of the polished surface after finishing polish (stripped plane) was measured on the

250-micron square with the phase shift interference method and it measured again on the 1-micron square by the atomic force microscope method, they were an average of 0.25nm and 0.19nm in the RMS value (square mean square root granularity), respectively. While this value is equivalent to the surface roughness of the usual silicon wafer by which mirror polishing was carried out and it turns out that the remarkable improvement was achieved, it turns out that this reworked exfoliation wafer is a thing reusable as a silicon wafer.

[0051] So, in this example, the reworked exfoliation wafer was used as a base wafer like drawing 2 (G). That is, the reuse wafer was used as a base wafer 1 of drawing 1 (a). Since 8 microns of exfoliation wafers were thickened from the first, the thickness after rework is the request thickness of the base wafer used by drawing 1 R> 1 (a). the place which produced the SOI wafer by the hydrogen ion exfoliating method according to the process of drawing 1 after that -- the high quality SOI wafer of a passage was usually producible satisfactory.

[0052] In addition, this invention is not limited to the above-mentioned operation gestalt. The above-mentioned operation gestalt is instantiation, and no matter it may be what thing which has the same configuration substantially with the technical thought indicated by the claim of this invention, and does the same operation effectiveness so, it is included by the technical range of this invention.

[0053] For example, although explained focusing on the case where combine two silicon wafers above and a SOI wafer is produced, it is not limited in this case and combines with an insulating wafer after an ion implantation to a silicon wafer, and naturally this invention can be applied, also when adding reprocessing to the exfoliation wafer which carries out a byproduction when exfoliating a silicon wafer and manufacturing a SOI wafer.

[0054] Moreover, it is not limited to what was shown in drawing 2 , and other processes, such as washing and heat treatment, may be added to this process, or exchange of the order of a process, an abbreviation, etc. can also perform reprocessing steps of the exfoliation wafer of this invention suitably according to the purpose a part.

[0055]

[Effect of the Invention] As explained above, according to this invention, suitable reprocessing can be performed to the exfoliation wafer which carried out the byproduction in the hydrogen ion exfoliating method, and it can actually reuse now as a silicon wafer to it. That is, by this invention, the level difference of the wafer circumference which poses a problem with an exfoliation wafer, the damage layer by the ion implantation, and surface roughness can be removed, and the problem of the abnormalities in resistivity by an oxygen donor's generation based on exfoliation heat treatment can also be eliminated. Therefore, a cost cut can be aimed at with improvement in the remarkable productivity of a SOI wafer.

[Translation done.]

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TECHNICAL FIELD

[Field of the Invention] This invention relates to the approach of adding reprocessing to the exfoliation wafer which exfoliates after combining the wafer which carried out the ion implantation, and manufactures a SOI (silicon on insulator) wafer and by which a byproduction is carried out in the so-called hydrogen ion exfoliating method (called the smart cutting method), and reusing as a silicon wafer.

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PRIOR ART

[Description of the Prior Art] SIMOX (separation by implanted oxygen) which heat-treats at an elevated temperature and forms an oxide film after driving oxygen ion into a silicon single crystal by high concentration as a method of producing the wafer of SOI structure conventionally -- they are what is depended on law, and the technique in which the joining-together method which combines two silicon wafers which carried out mirror polishing, without using adhesives, and thin-film-izes wafer of one of the two attracts attention.

[0003] SIMOX -- since law can determine and control the thickness of the SOI layer used as a device active region by acceleration voltage at the time of oxygen ion implantation -- a thin layer -- and although there is an advantage which can obtain the high SOI layer of thickness homogeneity easily, the dependability of an embedding oxide film, the crystallinity of a SOI layer, and heat treatment at the temperature of 1300 degrees C or more are required -- etc. -- there are many problems.

[0004] On the other hand, the wafer joining-together method forms an oxide film at least in one side between two silicon mirror plane wafers of a single crystal. Join without using adhesives and association is strengthened with subsequently adding heat treatment (usually 1100 degrees C - 1200 degrees C). Since mirror polishing of the front face of a thin film is carried out and a SOI layer is formed after thin-film-izing wafer of one of the two by grinding or wet etching after that, there is an advantage that the dependability of an embedding oxide film is high and the crystallinity of a SOI layer is also good.

[0005] However, by thin-film-izing taking serious time amount upwards, since it has thin-film-ized by mechanical processing, and wafer of one of the two serves as powder etc. and it disappears, productivity will be low and will become remarkable cost quantity. And in the grinding and polish by machining, there is a fault that there is a limitation also in the thickness of the SOI layer obtained and its homogeneity. in addition, not only when the wafer joining-together method combines silicon wafers, but a silicon wafer, SiO₂ and SiC, and aluminum 2O₃ etc. -- it may couple directly with an insulating wafer and a SOI layer may be formed

[0006] How to exfoliate after combining the wafer which carried out the ion implantation as the manufacture approach of a SOI wafer recently, and to manufacture a SOI wafer

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EFFECT OF THE INVENTION

It will become suitable in order to demonstrate the (IG effectiveness). Moreover, if an exfoliation wafer is used as the base wafer or bond wafer at the time of producing a SOI wafer, since one SOI wafer can be obtained from one silicon wafer on parenchyma, the manufacturing cost of a SOI wafer can be decreased remarkably.

[0038] In addition, although the exfoliation wafer reworked by this invention is reused as a desired silicon wafer, it thickens thickness of the bond wafer which is an exfoliating near wafer which is beforehand used in the hydrogen ion exfoliating method a little from the thickness for which it is needed with a reuse wafer, and it is made to serve as thickness of the wafer considered as a request in reuse after rework by polish.

[0039] However, as mentioned above, in order to remove the surrounding level difference of an exfoliation wafer by polish by this invention, it is based also on the thickness of a SOI layer, but even if it can remove a level difference completely by about 1 micron [at most] polish cost and performs washing accompanied by subsequent finishing polish and etching etc., a machining allowance 10 microns or less is enough on the whole. Thickening thickness of the bond wafer to be used beforehand also seems therefore, not to become a problem.

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TECHNICAL PROBLEM

[Problem(s) to be Solved by the Invention] When a SOI wafer is produced by such hydrogen ion exfoliating method, the byproduction of the one exfoliation wafer of silicon will be carried out inevitably. Conventionally, since one SOI wafer was obtained from one silicon wafer on parenchyma by reusing this exfoliation wafer that carried out the byproduction in the hydrogen ion exfoliating method, it was supposed that cost can be lowered sharply.

[0008] However, the example for which a certain thing actually reused reuse of such an exfoliation wafer as a concept was unknown in what [for there to be nothing and reuse how concretely]. In investigation of this invention persons, if especially the exfoliation wafer remained as it was, it turned out that a level difference is around a wafer, the damage layer by the ion implantation exists in a front face, or surface roughness is large so that it cannot be used as a usual silicon mirror plane wafer. And when the exfoliation wafer has received heat treatment for exfoliation at least and CZ wafer is used, in the wafer, precipitation of oxygen may be started or resistivity may have separated sharply to the request value by an oxygen donor's generation.

[0009] Then, this invention was made in view of such a trouble, performs suitable reprocessing for the exfoliation wafer which carried out the byproduction in the hydrogen ion exfoliating method, offers an approach actually reusable as a silicon wafer, and actually aims at aiming at a cost cut to improvement in the productivity of a SOI wafer.

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MEANS

[Means for Solving the Problem] Invention indicated to claim 1 of this invention in order to solve the above-mentioned technical problem is the approach of reusing the exfoliation wafer characterized by performing polish which removes a surrounding level difference to an exfoliation wafer at least as said reprocessing in the approach of adding reprocessing to the exfoliation wafer by which a byproduction is carried out in case a SOI wafer is manufactured by the hydrogen ion exfoliating method, and reusing as a silicon wafer.

[0011] Thus, to the exfoliation wafer which carried out the byproduction by the hydrogen ion exfoliating method, it became clear that there was a level difference on the outskirts. So, in this invention, it decided to remove by grinding a surrounding level difference as reprocessing of an exfoliation wafer. If polish removes the surrounding level difference of an exfoliation wafer, while a surrounding level difference is easily removable, removal of the damage layer of an exfoliation wafer front face and the improvement of surface roughness are also made to coincidence.

[0012] In this case, as indicated to claim 2, it is desirable as reprocessing of an exfoliation wafer to carry out finishing polish after the polish which removes a surrounding level difference. This is because the direction ground in two or more steps can make better surface roughness or display flatness of a polished surface etc. rather than finishing a polished surface only by the polish which removes a surrounding level difference, and it can consider as the reuse wafer of high quality. And since there is not necessarily no need of also performing finishing polish in one step, you may carry out by two steps or more than it.

[0013] Moreover, as indicated to claim 3, it is desirable to remove the scaling film as reprocessing of an exfoliation wafer before the polish which removes a surrounding level difference. Thus, if the scaling film is removed before the polish which removes a surrounding level difference, it can grind to homogeneity. That is, if the oxide film has adhered to the surrounding level difference section, it will turn to a bigger level difference up, and it will become difficult to grind an oxide film to homogeneity in polish, since silicon differs from a degree of hardness.

[0014] Moreover, invention indicated to claim 4 of this invention is an approach characterized by performing donor killer heat treatment to an exfoliation wafer during rework of an exfoliation wafer. Since the oxygen donor generated in the exfoliation wafer by exfoliation heat treatment etc. by performing donor killer heat treatment is eliminable, the resistivity anomaly of an exfoliation wafer can be lost.

[0015] Invention indicated to claim 5 of this invention next, the exfoliation wafer reworked by any 1 term of said claim 1 thru/or claim 4 by the approach of a publication Are the approach of reusing as a base wafer of a SOI wafer, and invention indicated to claim 6 of this invention The exfoliation wafer reworked by any 1 term of said claim 1 thru/or claim 4 by the approach of a publication It is the approach of reusing as a bond wafer of a SOI wafer, and invention indicated to claim 7 of this invention is the approach of reusing the exfoliation wafer reworked by any 1 term of said claim 1

thru/or claim 4 by the approach of a publication as a silicon mirror plane wafer further.

[0016] Thus, since the front face is ground by homogeneity, the exfoliation wafer reworked by this invention can be used as the base wafer or bond wafer in the case of sticking two silicon wafers and producing a SOI wafer, and can be used also as a usual silicon mirror plane wafer. Since precipitation of oxygen has occurred by exfoliation heat treatment etc. in the reworked exfoliation wafer in using the exfoliation wafer by which the byproduction was especially carried out from CZ wafer as a base wafer or a usual silicon mirror plane wafer, it will become suitable in order that this may demonstrate the gettering effectiveness. Moreover, since there are no crystal defects, such as COP (Crystal Originated Particle) and an oxygen sludge, like CZ wafer in the case of the exfoliation wafer [wafer / FZ] which has the exfoliation wafer or epitaxial layer by which the byproduction was carried out, it is suitable to reuse as a bond wafer.

[0017] And invention indicated to claim 8 of this invention is a silicon wafer with which the reuse characterized by being reworked by any 1 term of said claim 1 thru/or claim 4 by the approach of a publication is presented. As mentioned above, the exfoliation wafer reworked by this invention turns into a wafer reusable as a silicon wafer. In this case, what is necessary is to thicken thickness of the exfoliating near wafer which is beforehand used in the hydrogen ion exfoliating method, and just to make it become the thickness of the wafer considered as a request in reuse after rework by polish.

[0018]

[Embodiment of the Invention] Although the gestalt of operation of this invention is explained hereafter, referring to a drawing, this invention is not limited to these. Here, drawing 1 is the flow Fig. showing an example of the production process of the SOI wafer by the approach of manufacturing a SOI wafer by the hydrogen ion exfoliating method. Moreover, drawing 2 is the process flow Fig. showing an example of the approach of reworking and reusing the exfoliation wafer of this invention.

[0019] Hereafter, this invention is explained focusing on the case where two silicon wafers are combined. First, in the hydrogen ion exfoliating method of drawing 1, at a process (a), two silicon mirror plane wafers are prepared and the bond wafer 2 used as the base wafer 1 used as the pedestal suitable for the specification of a device and a SOI layer is prepared. Next, at a process (b), one [at least] wafer of them is oxidized thermally, the bond wafer 2 is oxidized thermally here, and the oxide film 3 of about 0.1 micrometers - 2.0 micrometer thickness is formed in the front face.

[0020] Inject a hydrogen ion or rare gas ion into a front face to one side of the bond wafer 2 in which the oxide film was formed, the minute air-bubbles layer (enclosure layer) 4 parallel to a front face is made to form in it in the average penetration depth of ion at a process (c), and this impregnation temperature has desirable 25-450 degrees C. A process (d) is a process which piles up and sticks the base wafer 1 to the hydrogen ion impregnation side of the bond wafer 2 which carried out hydrogen ion impregnation through an oxide film, and wafers paste it up by contacting the front faces of two wafers under the pure ambient atmosphere of ordinary temperature, without using adhesives etc.

[0021] Next, a process (e) is an exfoliation heat treatment process divided into the exfoliation wafer 5 and the SOI wafer 6 (SOI layer 7+ pad oxide film 3+ base wafer 1) by exfoliating bordering on the enclosure layer 4, for example, if heat treatment is added at the temperature of about 500 degrees C or more under an inert gas ambient atmosphere, it will be divided into the exfoliation wafer 5 and the SOI wafer 6 by the rearrangement of a crystal, and condensation of air bubbles.

[0022] And at a process (f), in the bonding strength of the wafers stuck by the adhesion process and exfoliation heat treatment process of said process (d) and (e), since it is weak for using it at a device process as it is, as heat-of-linkage processing, hot heat treatment is performed to the SOI wafer 6, and let bond strength be sufficient thing. It is desirable to perform this heat treatment in 2 hours from 30 minutes at 1050 degrees C - 1200 degrees C for example, under an inert gas ambient atmosphere. In addition, exfoliation heat treatment of a process (e) and heat-of-linkage processing of a process (f)

may be performed continuously, and exfoliation heat treatment of a process (e) and heat-of-linkage processing of a process (f) may be performed as that as which it serves to coincidence.

[0023] Next, a process (g) is a process of very little mirror polishing of the polish cost called a touch polish, and is a process which removes removal and surface roughness of the crystal defect layer which exists in the cleavage plane which is a front face of the SOI layer 7. The SOI wafer 6 of the high quality which crystal quality is high and has the high SOI layer 7 of thickness homogeneity through the above process can be manufactured (process (h)).

[0024] In such a hydrogen ion exfoliating method, the byproduction of the exfoliation wafer 5 will be carried out in the drawing 1 (e) process. Since the thickness of the SOI layer produced by the hydrogen ion exfoliating method is usually 2 microns or less in about 0.1-1.5 microns as it is thick, the exfoliation wafer 5 has sufficient thickness. Therefore, if this is reused as a silicon wafer, it will become possible to lower the manufacturing cost of a SOI wafer remarkably.

[0025] However, as the extension mimetic diagram of an exfoliation wafer was shown in drawing 2 (A), it turned out that a level difference 10 occurs in the periphery of this exfoliation wafer 5, and it becomes what cannot be used as a silicon wafer if it remains as it is. The level difference 10 of the circumference of this is generated from becoming uncombined, without combining the periphery of a bond wafer with a base wafer. Therefore, the height of this level difference becomes the thing of extent which embedded with the thickness of a SOI layer and added the thickness of an oxide film 3.

[0026] Moreover, in the stripped plane 11 of an exfoliation wafer, the damage layer 12 by hydrogen ion impregnation remained, and the surface roughness was also found by that it is bad at it compared with the usual mirror plane wafer. When local surface roughness was bad and performed etching with selectivity like alkali etching especially, it turned out that a deep pit will be formed.

[0027] Furthermore, this exfoliation wafer 5 has received exfoliation heat treatment of about 500 degrees C or more at least, and it may produce un-arranging, as an oxygen donor occurs and resistance of a wafer indicates outlying observation to be, when the wafer containing oxygen like CZ wafer is used as a bond wafer.

[0028] Then, that the above problems should be solved, this invention persons perform suitable reprocessing for the exfoliation wafer which carried out the byproduction in the hydrogen ion exfoliating method, and as a result of examining how to actually reuse as a silicon wafer, they result in this invention. That is, first, by this invention, when manufacturing a SOI wafer by the hydrogen ion exfoliating method, polish removed the level difference of the circumference produced to the exfoliation wafer by which a byproduction is carried out.

[0029] Thus, if polish removes the surrounding level difference of an exfoliation wafer, a surrounding level difference is easily removable. For example, when the thickness of a SOI layer is 0.2 microns, a level difference can be completely removed by about 1-micron polish cost. And in case polish removes a surrounding level difference, removal of the damage layer of an exfoliation wafer front face and the improvement of surface roughness are also made to coincidence.

[0030] In this case, as reprocessing of an exfoliation wafer, it is desirable to carry out finishing polish after the polish which removes a circumference level difference. This is because the direction ground in two or more steps using abrasives with a more fine eye can make better surface roughness, display flatness, etc. of a polished surface rather than finishing a polished surface only by the polish which removes a surrounding level difference, and quality equivalent to the surface roughness of the usual silicon mirror plane wafer or display flatness can be attained. In addition, there is not necessarily no need of also performing this finishing polish in one step, and it may be performed by two steps or more than it.

[0031] Moreover, in this invention, it is desirable to remove the scaling film 3 as reprocessing of an exfoliation wafer before the polish which removes a surrounding level difference. This is because the

direction which removes the scaling film 3 before the polish which removes the surrounding level difference 10 can grind to homogeneity. That is, when the oxide film 3 has adhered to the surrounding level difference section 10, a level difference will become higher and an oxide film is because silicon differs from a degree of hardness, so the inside of an exfoliation wafer side becomes is hard to be ground in homogeneity. Removal of an oxide film can perform an exfoliation wafer easily by being immersed into fluoric acid.

[0032] In this way, the damage layer by the level difference in an exfoliation wafer periphery and the hydrogen ion impregnation in a stripped plane and the surface roughness of a stripped plane can be removed, and a reuse wafer with the front face which any inferiority does not have compared with the usual mirror plane wafer can be obtained.

[0033] Moreover, when an exfoliation wafer is a CZ wafer in this invention, it is desirable to perform donor killer heat treatment during rework of an exfoliation wafer. Since an exfoliation wafer exfoliates by exfoliation heat treatment of about 500 degrees C or more, it will have received such [naturally] low-temperature heat treatment. If low-temperature heat treatment is performed to the silicon wafer which contains oxygen like CZ wafer, an oxygen donor will occur, for example, it is known well that phenomena, like the resistivity of a p-type silicon wafer becomes high unusually may arise. Therefore, also in the exfoliation wafer by which a byproduction is carried out by the hydrogen ion exfoliating method, by exfoliation heat treatment, an oxygen donor may arise and the resistivity of an exfoliation wafer may become unusual. for this reason -- for example, in case the thickness of a wafer is measured, the problem that thickness of an exfoliation wafer cannot be measured with the measuring instrument of the capacitive sensing method currently generally used arises.

[0034] Therefore, in this invention, by performing donor killer heat treatment during rework, the oxygen donor generated in the exfoliation wafer is eliminated, and the resistivity anomaly of an exfoliation wafer was lost by exfoliation heat treatment etc. What is necessary is just made to carry out heat treatment for 20 minutes as an approach which should just add heat treatment of 600 degrees C or more, and is commonly used as this donor killer heat treatment as generally carried out, for example at 650 degrees C.

[0035] And during rework of an exfoliation wafer, before that washing or etching of a wafer is performed heat-treats as mentioned above many especially, washing and etching are performed in many cases so that a wafer may not be polluted in heat treatment. In this case, since a cure, such as a deep pit being formed and making [many] polish cost at a next polish process, is needed when etching or washing with selectivity like alkali etching is performed, since local surface roughness is bad and also has a damage layer, an exfoliation wafer like this invention is not desirable.

[0036] In this way, since it has the field condition ground by the completely same homogeneity as the usual silicon mirror plane wafer, the silicon wafer reworked by the approach of above-mentioned this invention can be used as a raw material wafer of a lamination SOI wafer, and may be used as a silicon wafer for production of the usual integrated circuit etc. Moreover, you may use as the so-called substrate of an epitaxial wafer, and especially the application of the reuse is not limited.

[0037] In this case, since precipitation of oxygen has occurred in the reworked exfoliation wafer by the thermal oxidation processing before hydrogen ion impregnation (usually 900 degrees C or more), and exfoliation heat treatment of about 500 degrees C or more in using the exfoliation wafer with which this invention was reworked as a base wafer or a usual silicon mirror plane wafer, this is the so-called in thorin chic gettering effectiveness.

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EXAMPLE

[Example] Although the example of this invention is given and being explained concretely hereafter, this invention is not limited to these.

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DESCRIPTION OF DRAWINGS

[Brief Description of the Drawings]

[Drawing 1] (a) - (h) is the flow Fig. showing an example of the production process of the SOI wafer by the hydrogen ion exfoliating method.

[Drawing 2] (A) - (G) is the process flow Fig. of the approach of reusing the exfoliation wafer of this invention adopted in the example.

[Drawing 3] It is the measurement result Fig. of the surrounding level difference of an exfoliation wafer. (A) After an unsettled exfoliation wafer, (B) oxide-film removal, and (C) circumference level difference removal.

[Drawing 4] It is a Fig. as a result of investigating the relation between the machining allowance of circumference level difference polish, and the height of a level difference.

[Description of Notations]

1 -- Base wafer 2 -- Bond wafer 3 [5 / 7 -- SOI layer 10 / 12 -- Damage layer. / -- A surrounding level difference 11 -- Stripped plane / -- An exfoliation wafer 6 -- SOI wafer] -- An oxide film, 4 -- Hydrogen ion impregnation minute air-bubbles layer (enclosure layer)

[Translation done.]

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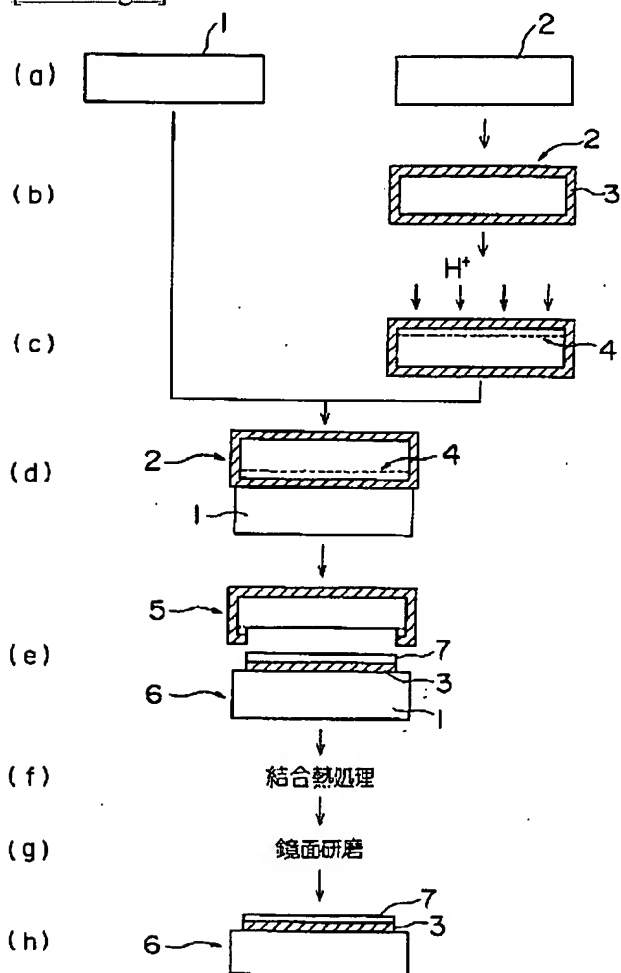
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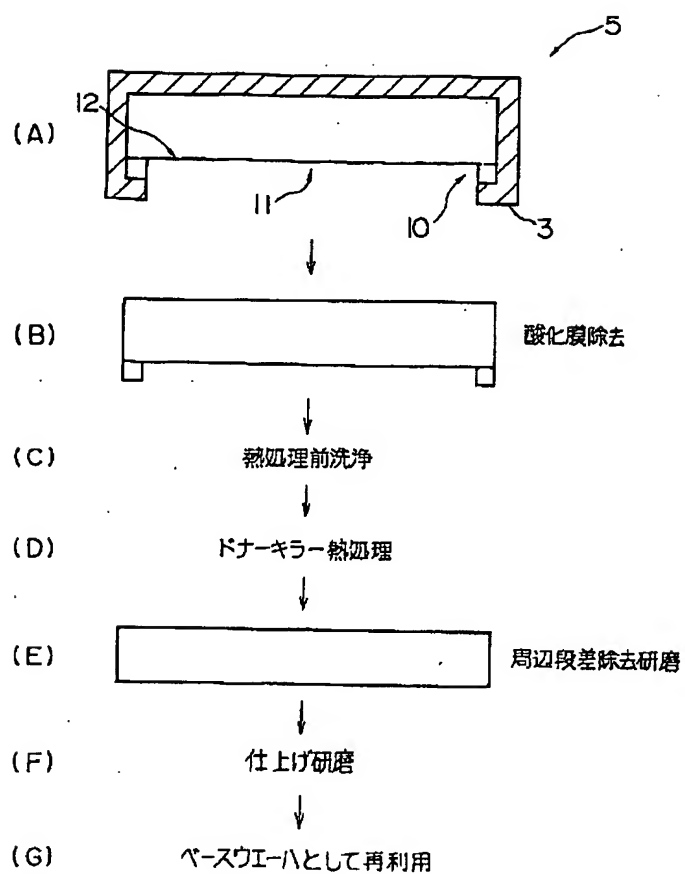
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DRAWINGS

[Drawing 1]

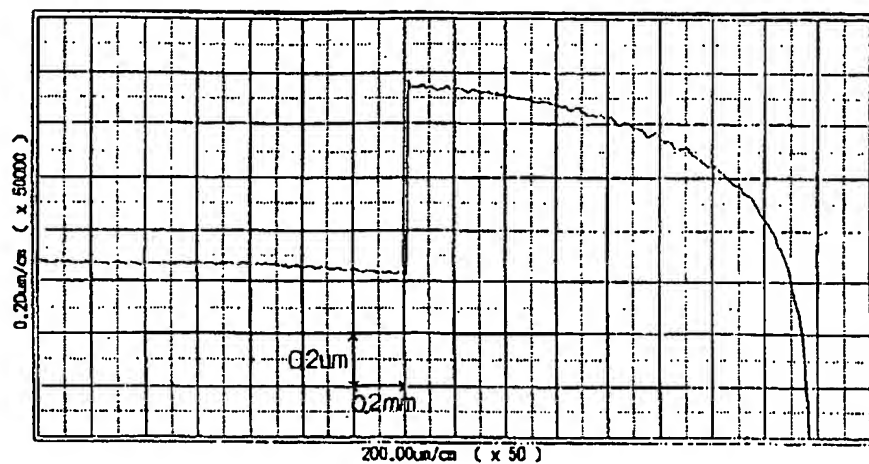


[Drawing 2]

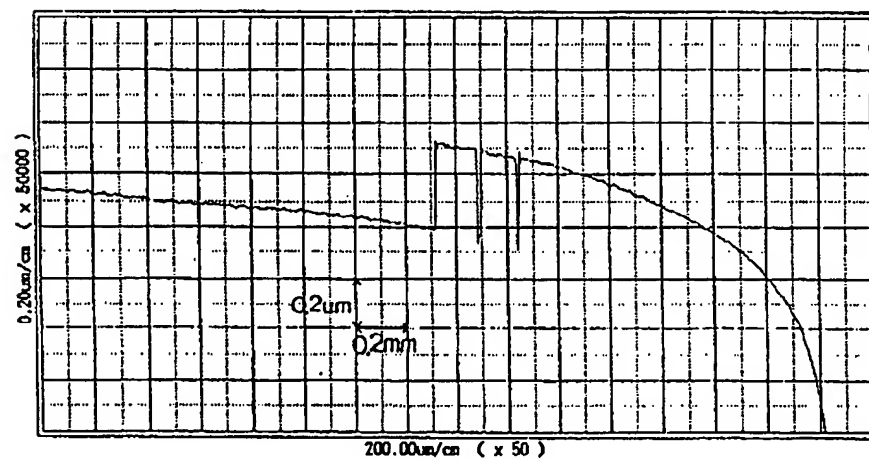


[Drawing 3]

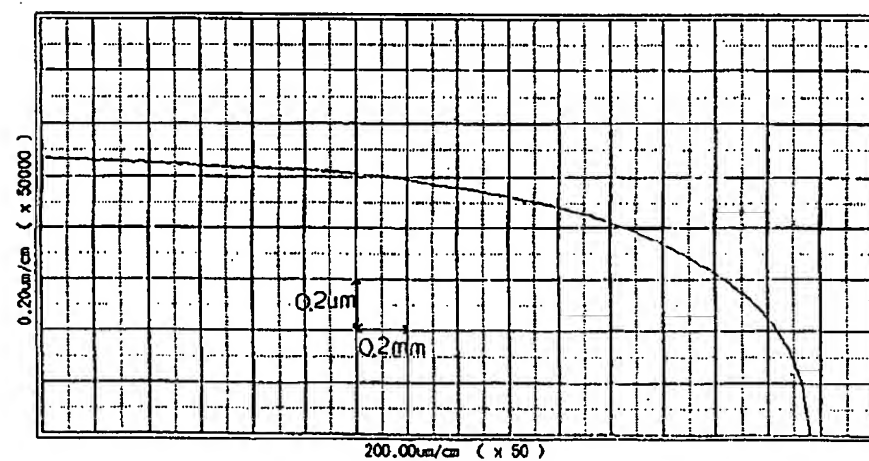
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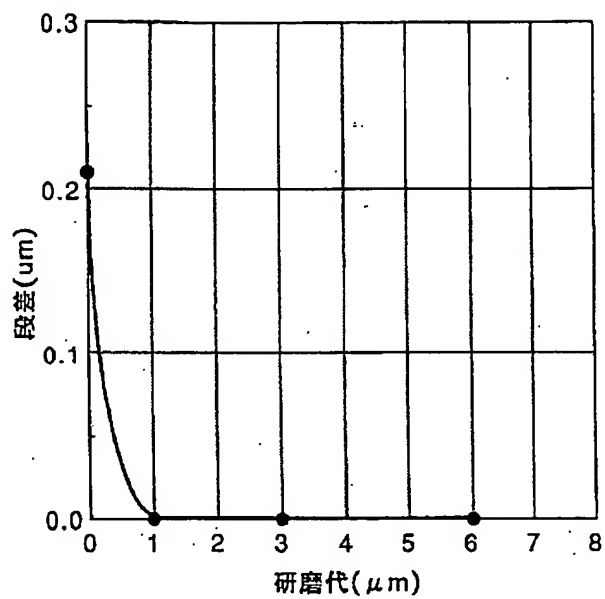
(B)



(C)



[Drawing 4]



[Translation done.]